| Basic information | |
|---|---|
| **2018/2604(DEA)**<br><br>DEA - Delegated acts procedure | Procedure completed - delegated act enters into force |
| Exemption for lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors<br><br>Supplementing 2008/0240(COD)<br><br>**Subject**<br><br>3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport) | |

| Technical information | |
|---|---|
| **Procedure reference** | 2018/2604(DEA) |
| **Procedure type** | DEA - Delegated acts procedure |
| **Procedure subtype** | Examination of delegated act |
| **Amendments and repeals** | Supplementing 2008/0240(COD) |
| **Stage reached in procedure** | Procedure completed - delegated act enters into force |
| **Committee dossier** | ENVI/8/12355 |